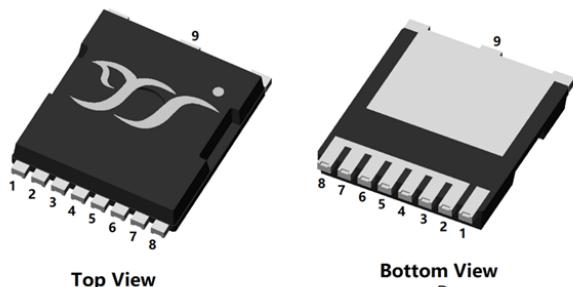
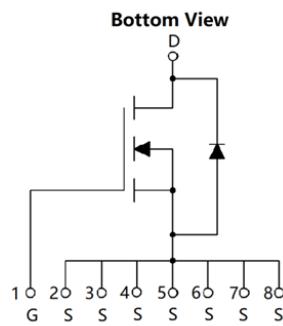


## N-Channel Enhancement Mode Field Effect Transistor


**TOLL**


### Product Summary

- $V_{DS}$  200V
- $I_D$  102A
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ )  $<10.7m\Omega$
- 100% EAS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

### Applications

- UPS and Inverter applications
- Motor drivers
- DC-DC convertor

### ■ Limiting Values

Parameter	Conditions		Symbol	Min	Max	Unit	
Drain-source Voltage	$T_A=25^\circ C, V_{GS}=10V$		$V_{DS}$	-	200	V	
Gate-source Voltage			$V_{GS}$	-20	20		
Continuous Drain Current (Note 1,2)	Steady-State	$T_A=100^\circ C, V_{GS}=10V$	$I_D$	-	11	A	
Continuous Drain Current (Note 1,3)		$T_C=25^\circ C, V_{GS}=10V$ , Chip limitation		-	7.7		
Pulsed Drain Current	$T_C=25^\circ C, t_p \leq 10\mu s$		$I_{DM}$	-	408		
Maximum Body-Diode Continuous Current	$T_C=25^\circ C$		$I_S$		102		
Avalanche energy (non-repetitive )	$T_J=25^\circ C, V_G=10V, R_G=25\Omega, L=0.5mH, IAS=50A$		EAS	-	625	mJ	
Total Power Dissipation (Note 1,2)	Steady-State	$T_A=25^\circ C$	$P_D$	-	3.4	W	
Total Power Dissipation (Note 1,3)		$T_A=100^\circ C$		-	1.7		
Junction and Storage Temperature Range	$T_C=25^\circ C$			-	300		
Junction and Storage Temperature Range	$T_C=100^\circ C$			-	150		

### ■ Thermal Resistance

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient (Note 2)	$R_{\theta JA}$	-	43	°C/W
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	0.5	

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJT011G20H	F1	YJT011G20H	2000	4000	20000	13" reel



## ■ Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA, T <sub>j</sub> =25°C	200	-	-	V
		V <sub>GS</sub> =0V, I <sub>D</sub> =10mA, T <sub>j</sub> =25°C	200	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =200V, V <sub>GS</sub> =0V, T <sub>j</sub> =25°C	-	-	1	μA
		V <sub>DS</sub> =200V, V <sub>GS</sub> =0V, T <sub>j</sub> =125°C	-	-	100	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V, T <sub>j</sub> =25°C	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA, T <sub>j</sub> =25°C	2.2	3	3.8	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =50A, T <sub>j</sub> =25°C	-	8.6	10.7	mΩ
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =50A, V <sub>GS</sub> =0V, T <sub>j</sub> =25°C	-	0.82	1.2	V
Gate Resistance	R <sub>G</sub>	f=1MHz, T <sub>j</sub> =25°C	-	0.8	-	Ω
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, f=1MHz, T <sub>j</sub> =25°C	-	3920	-	pF
Output Capacitance	C <sub>oss</sub>		-	445	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	11.3	-	
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =100V, I <sub>D</sub> =50A, T <sub>j</sub> =25°C	-	50.5	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	18.4	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	8.2	-	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =50A, di/dt=100A/μs, V <sub>GS</sub> =0V, V <sub>R</sub> =100V, T <sub>j</sub> =25°C	-	513	-	nC
Reverse Recovery Time	t <sub>rr</sub>		-	135	-	ns
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =100V, I <sub>D</sub> =50A, R <sub>GEN</sub> =3Ω, T <sub>j</sub> =25°C	-	20	-	ns
Turn-on Rise Time	t <sub>r</sub>		-	42	-	
Turn-off Delay Time	t <sub>D(off)</sub>		-	32	-	
Turn-off Fall Time	t <sub>f</sub>		-	9	-	

Note:

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- The value of R<sub>θJA</sub> is measured with the device mounted on the 40mm\*40mm\*1.1mm single layer FR-4 PCB board with 1 in<sup>2</sup> pad of 2oz. Copper, in the still air environment with T<sub>A</sub>=25°C. The maximum allowed junction temperature of 175°C. The value in any given application depends on the user's specific board design.
- Thermal resistance from junction to soldering point (on the exposed drain pad).

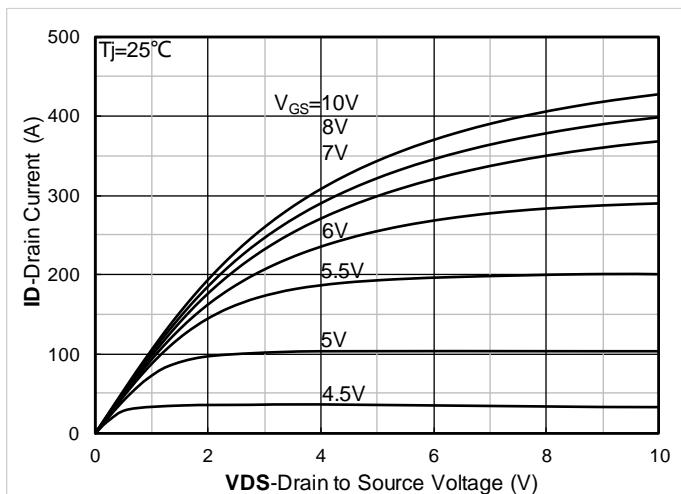
**■Typical Electrical and Thermal Characteristics Diagrams**

Figure 1. Output Characteristics; typical values

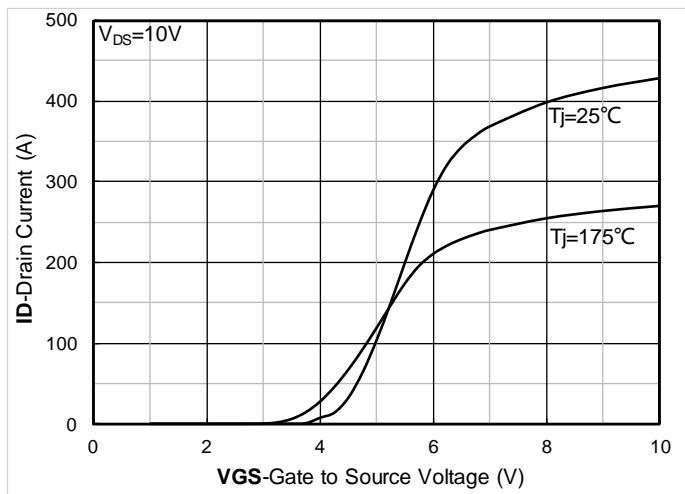


Figure 2. Transfer Characteristics; typical values

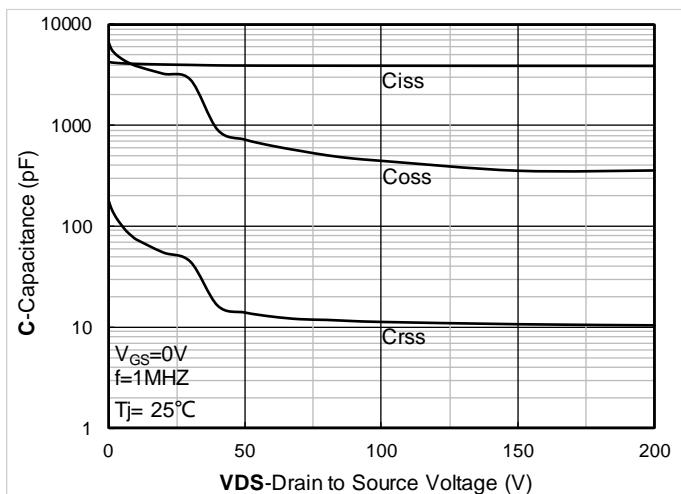


Figure 3. Capacitance Characteristics; typical values

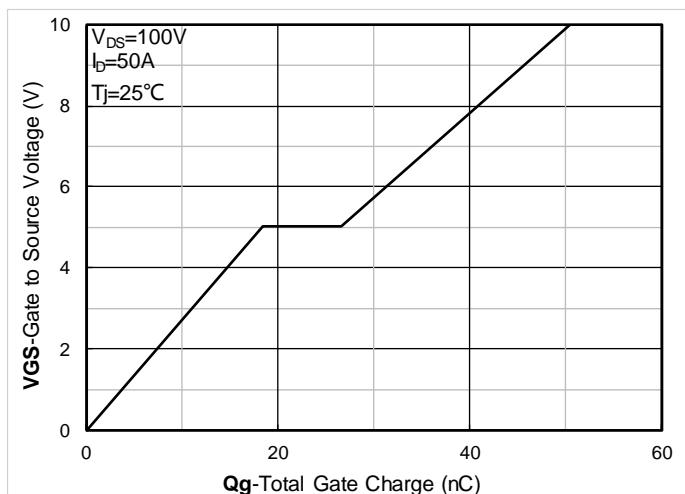


Figure 4. Gate Charge; typical values

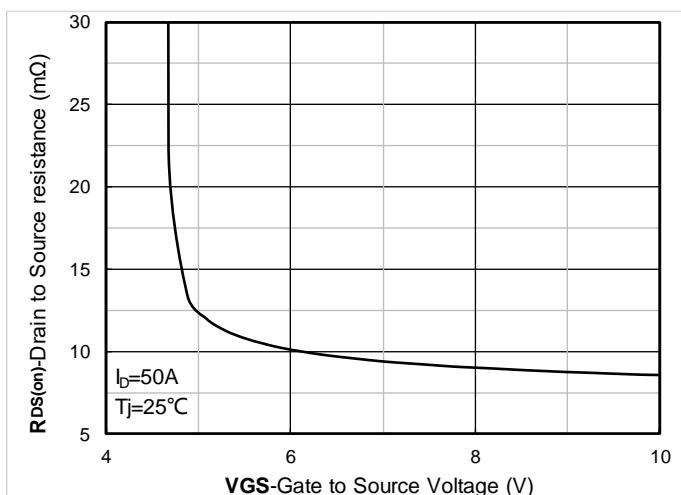


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

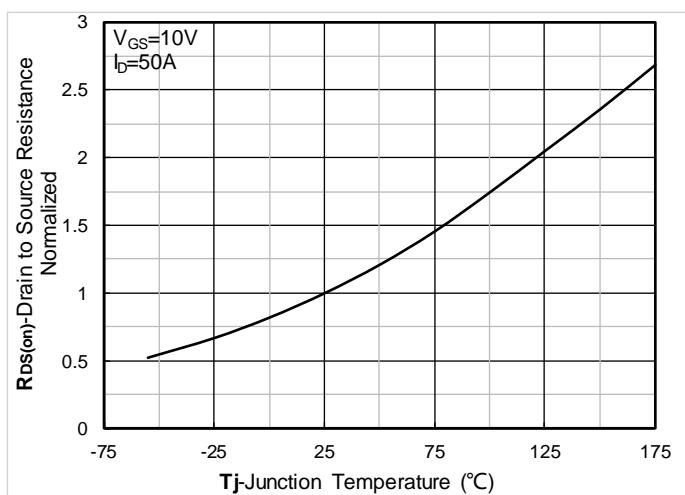


Figure 6. Normalized On-Resistance



**YJT011G20H**

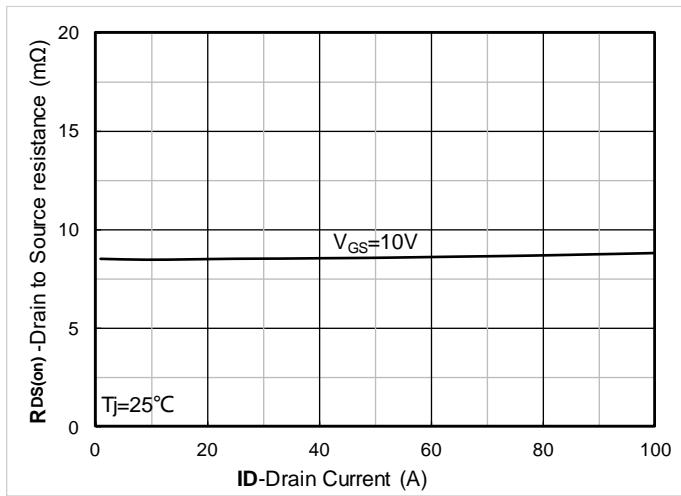


Figure 7.  $R_{DS(on)}$  vs. Drain Current; typical values

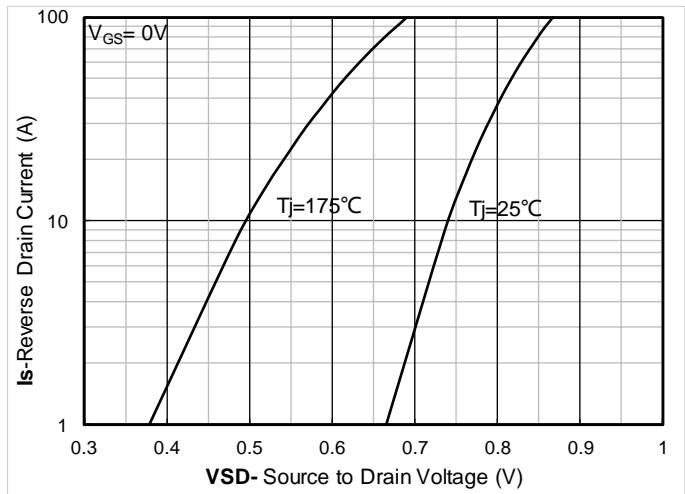


Figure 8. Forward characteristics of reverse diode; typical values

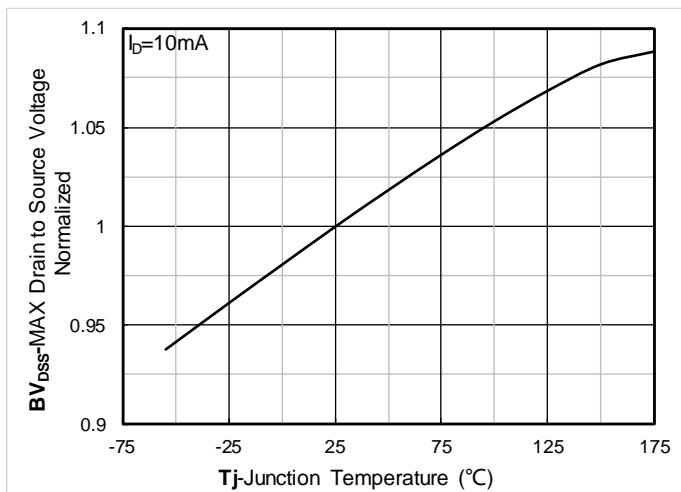


Figure 9. Normalized breakdown voltage

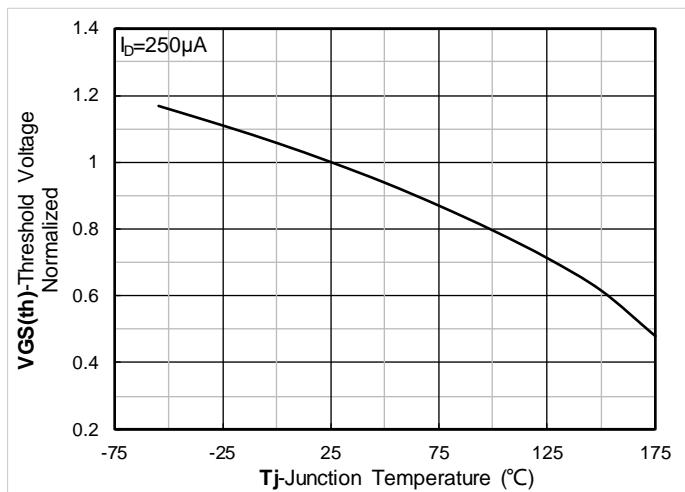


Figure 10. Normalized Threshold voltage

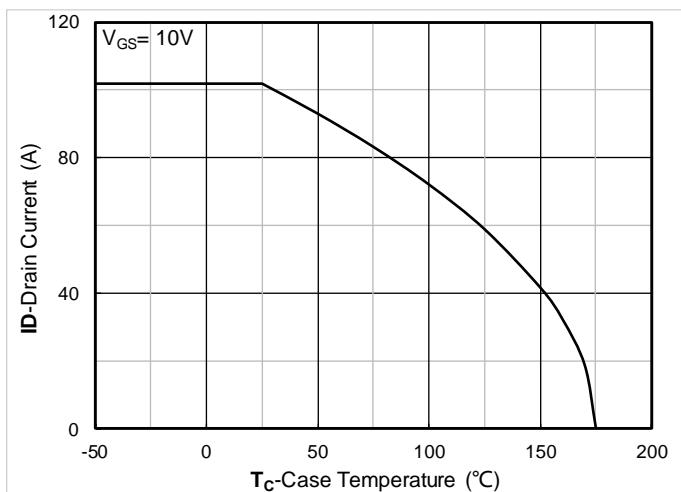


Figure 11. Current dissipation

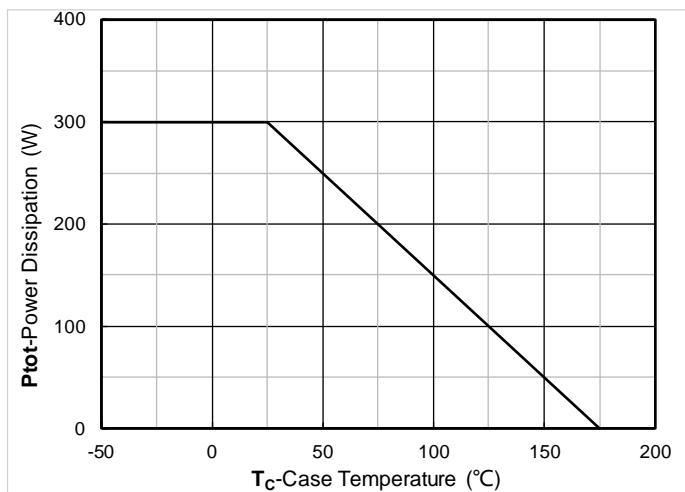


Figure 12. Power dissipation

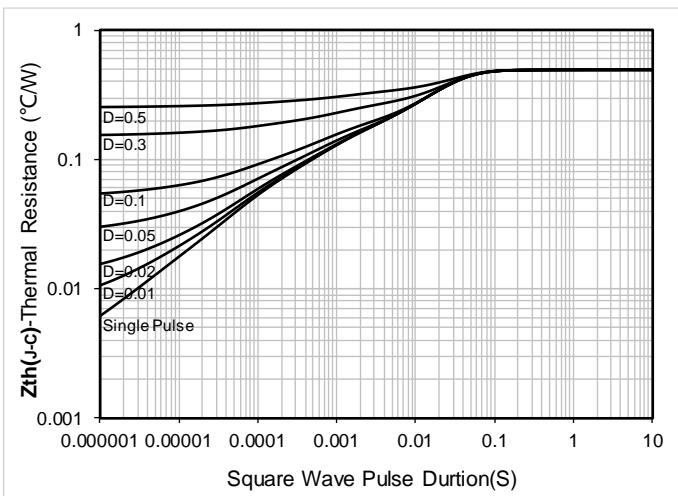


Figure 13. Maximum Transient Thermal Impedance

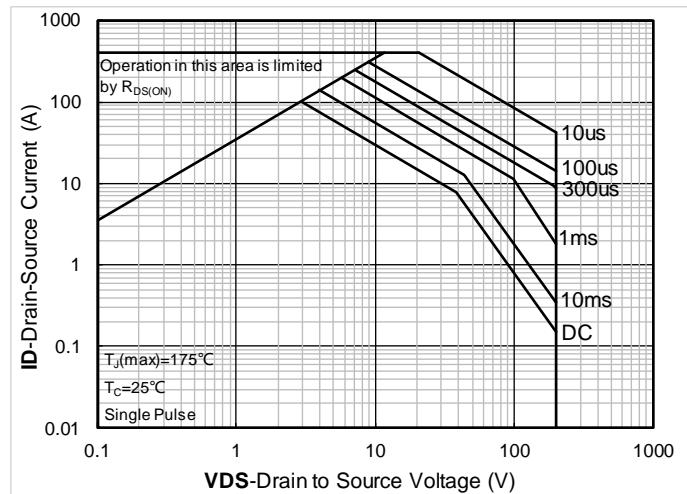


Figure 14. Safe Operation Area



## ■ Test Circuits &amp; Waveforms

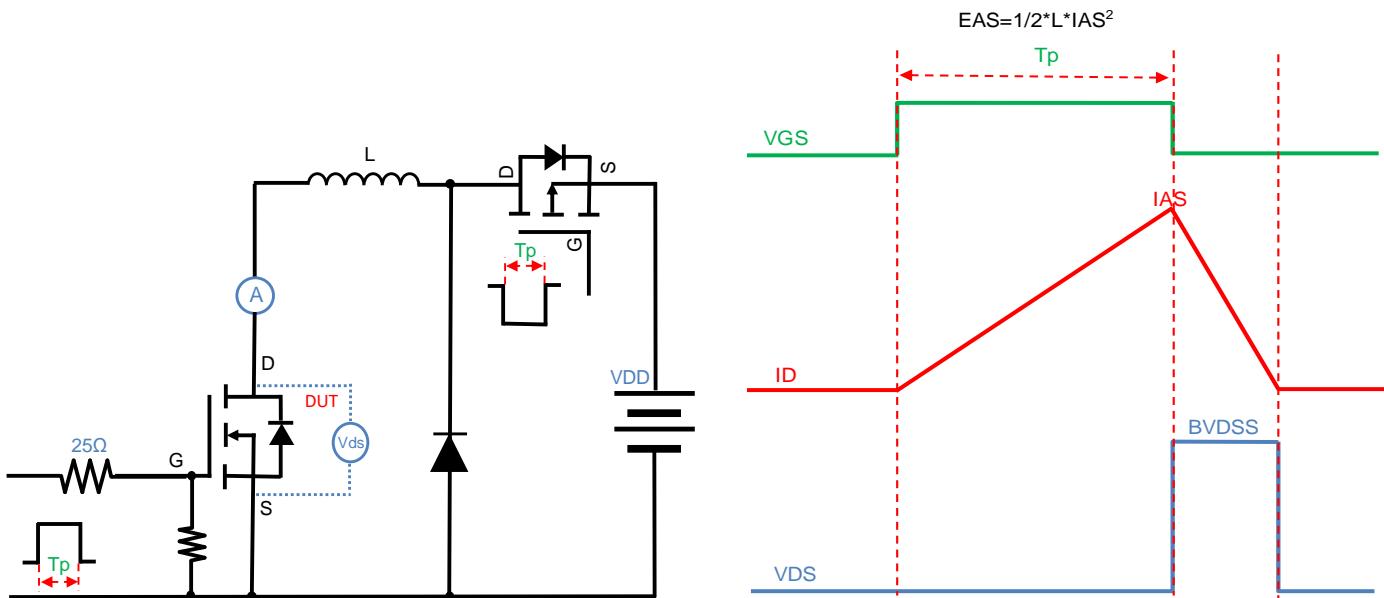


Figure A. Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveform

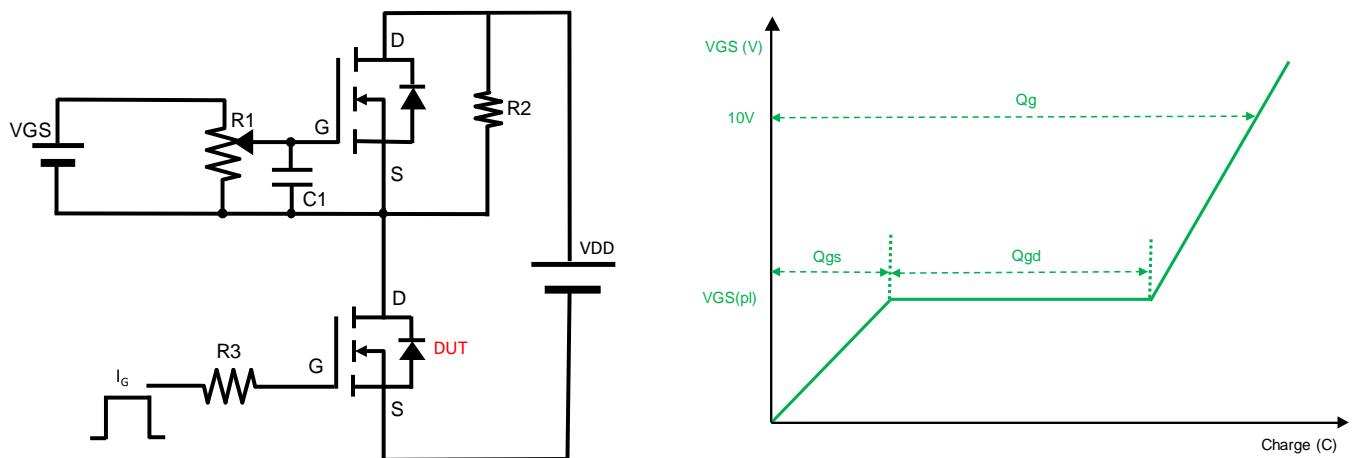


Figure B. Gate Charge Test Circuit &amp; Waveform

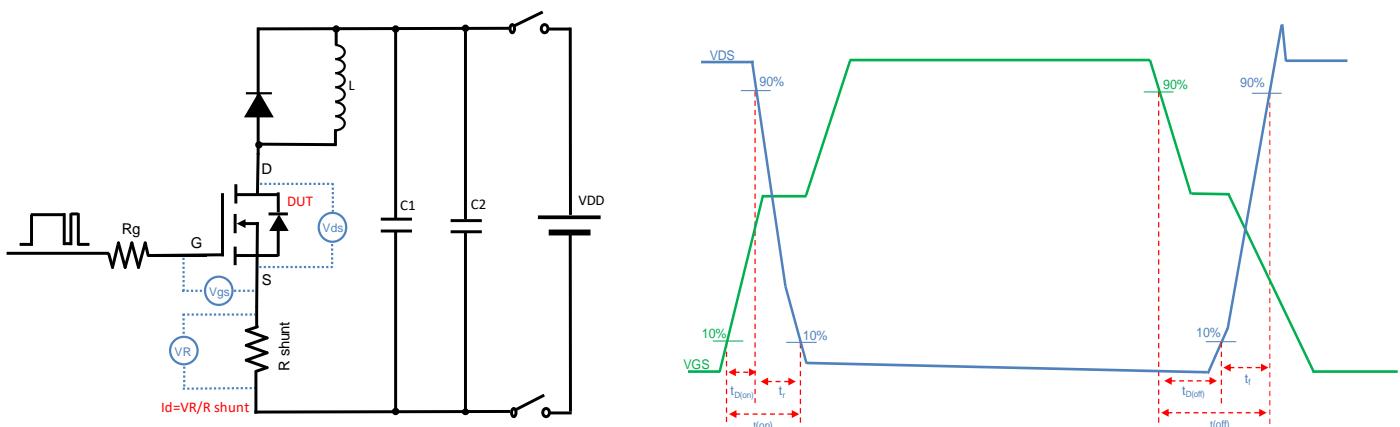


Figure C. Resistive Switching Test Circuit &amp; Waveform

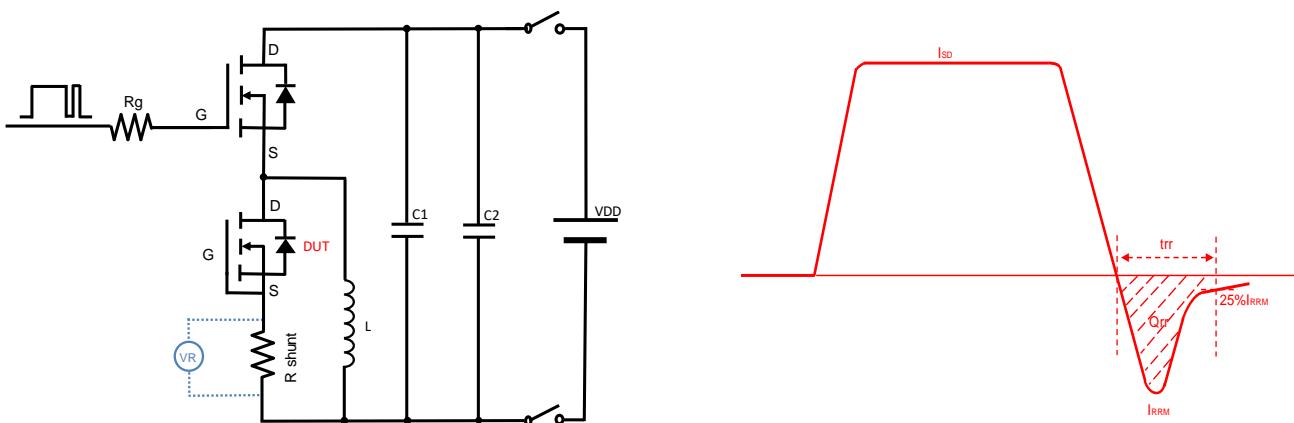
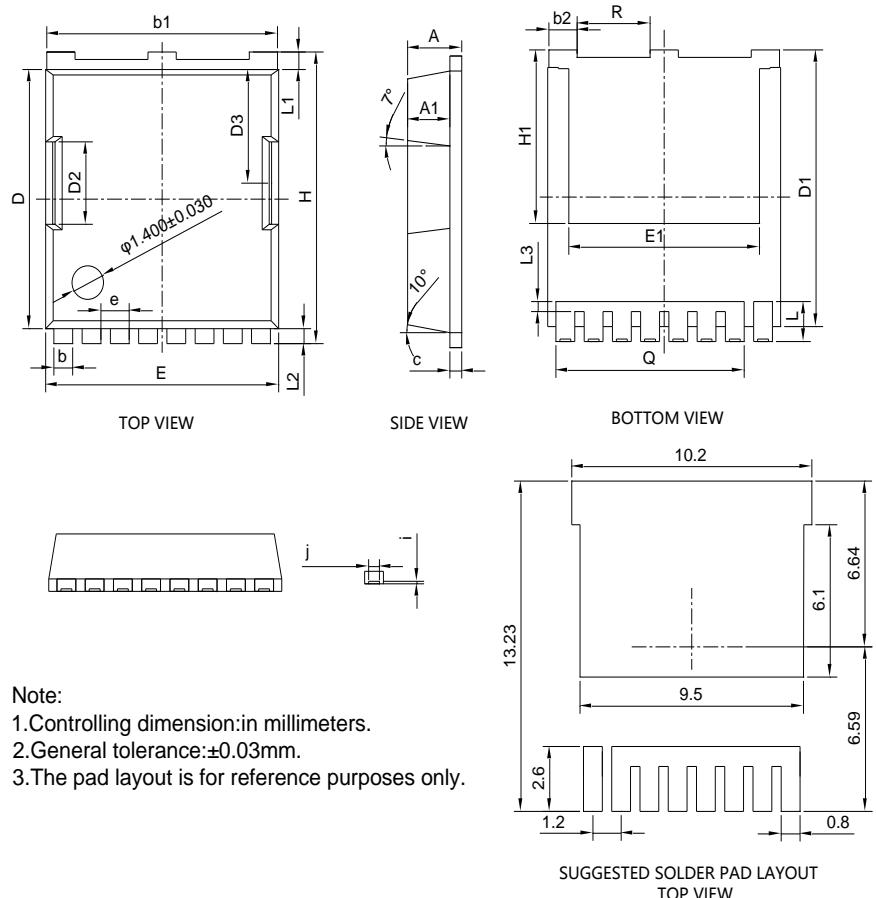


Figure D. Diode Recovery Test Circuit & Waveform



## ■TOLL Package information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.2	2.3	2.4
A1	1.7	1.8	1.9
b	0.7	0.8	0.9
b1	9.7	9.8	9.9
b2	1.1	1.2	1.3
c	0.4	0.5	0.6
D	10.28	10.38	10.48
D1	10.98	11.08	11.18
D2	3.2	3.3	3.4
D3	4.45	4.55	4.65
E	9.8	9.9	10
E1	8	8.1	8.2
e		1.2 BSC	
H	11.58	11.68	11.78
H1		6.95 BSC	
i		0.1 REF	
j		0.46 REF	
L	1.5	1.6	1.7
L1	0.6	0.7	0.8
L2	0.5	0.6	0.7
L3	0.3	0.4	0.5
Q		8 REF	
R	3.0	3.1	3.2

UNIT: mm



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